

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) An electronic microcircuit module tape including a mask and a substrate, at least one contact area on a first face of this substrate, a second opposite face of this substrate being capable of supporting an integrated circuit and being provided with cutouts exhibiting contact pad areas, wherein the tape further includes a first adhesive means to retain a first face of the mask in position against the second face of the substrate, and wherein the mask comprises a cutout forming a window adapted to subsequently receive the integrated circuit, and wherein the mask comprises at least a portion configured to remain with the substrate for permanent connection of a portion of the substrate to another member with the mask.

2. (Previously presented) The electronic microcircuit module tape according to claim 1, wherein the mask is made from a material identical to that of a card body provided to receive the module, from polyester or polyvinyl chloride.

3. (Previously presented) The electronic microcircuit module tape according to claim 1, wherein the mask has a thickness, defined with regard to the second face of the substrate on which it is mounted, greater than the height of the integrated circuit.

4. (Previously presented) The electronic microcircuit module tape according to claim 1, wherein the first adhesive means enables the integrated circuit to be retained on the substrate.

5. (Previously presented) A method for conditioning an electronic microcircuit module, characterised in that it includes the following stages consisting of

creating a contact area on a first face of a substrate tape,

arranging a first adhesive means between a second opposite face of the substrate tape and a first face of a mask tape, to keep the mask tape in position against the second face,

perforating the mask tape so that a mask window is facing the contact area, and

arranging a second adhesive means on the second face of the mask tape.

6. (Previously presented) The method according to claim 5, characterised in that it includes an additional stage consisting of:

choosing the mask tape in a material identical to that of a card on which the module is to be mounted.

7. (Previously presented) The method according to claim 5, characterised in that the mask tape has the form of a tape including several windows which are laminated on a support

including several contact area before separation into individual units.

8. (Previously presented) The method according to claim 5, characterised in that the stage consisting in retaining the mask tape in position against the second face of the substrate tape includes an operation consisting of:

laminating the first adhesive means on this second face of the substrate tape.

9. (Previously presented) The method according to claim 5, characterised in that the stage consisting in arranging the first adhesive means on the mask tape includes an operation consisting of

depositing the adhesive means on the mask tape, and then

perforating this mask tape before laminating it against the second face of the substrate tape.

10. (Previously presented) The method according to claim 5, characterised in that it includes a subsequent stage consisting in gluing an integrated circuit to the second face of the substrate tape, on the first adhesive means.

11. (Previously presented) The method according to claim 5, characterised in that it includes a stage consisting of:

gluing the mask tape equipped with an electronic circuit to the bottom of a card recess.

12. (Previously presented) The method according to claim 11, characterised in that the stage consisting in gluing the mask tape to the recess includes an operation consisting of:

depositing cyanoacrylate glue between the mask tape and the bottom of the recess.

13. (Previously presented) The method according to claim 11, characterised in that the stage consisting in gluing the mask tape into the recess includes an operation consisting of:

soldering by emission of ultrasound waves.

14. (Previously presented) The method according to claim 5, further comprising separating the individual module in the form of a parallelepiped.

15. (Previously presented) The electronic microcircuit module tape of claim 1, further comprising a second adhesive means dispensed on a second face of the mask.

16. (Currently amended) An electronic microcircuit module tape comprising:

a substrate tape having a first face and an opposite second face, wherein the second face is adapted to support a plurality of integrated circuits thereon;

a plurality of electrically conductive contact areas on the first face of the substrate tape; and

a mask tape having a first side attached to the second face of the substrate tape, wherein the mask tape comprises cutouts forming windows adapted to subsequently

receive the integrated circuits when the integrated circuits are attached to the second face of the substrate tape, wherein the windows are configured to allow insertion of the integrated circuits through the windows for subsequent mounting onto the second face of the substrate tape, and wherein the mask tape comprises at least a portion configured to remain with the substrate tape for permanent connection of a portion of the substrate tape to another member with the mask.

17. (Previously presented) An electronic microcircuit module tape as in claim 16 wherein the substrate tape comprises cutouts to allow access to the contact areas through the substrate tape from the windows.

18. (Currently amended) An electronic microcircuit module tape as in claim 16 wherein the substrate tape comprises a first adhesive layer to retain a first face of the mask ~~film~~ tape in position against the second face of the substrate ~~film~~ tape.

19. (Currently amended) An electronic microcircuit module tape as in claim 18 further comprising a second adhesive layer on a second opposite ~~side~~ face of the mask tape.

20. (Previously presented) An electronic microcircuit module tape as in claim 16 wherein the substrate tape and the mask tape are adapted to be cut into individual modules after the integrated circuits are attached to the second face of the substrate tape.

21. (Cancelled)

22. (New) An electronic microcircuit module tape as in claim 16 wherein the mask tape has a height greater than a height of the integrated circuit intended to be mounted on the second face of the substrate tape.

23. (New) A method for producing an electronic microcircuit module tape comprising the following steps performed in the following order:

depositing an electrically conductive layer on a first face of a substrate tape, wherein the substrate tape comprises a second opposite face;

gluing a first face of a mask tape on the second opposite face of the substrate tape; and

concurrent with or subsequent to the step of gluing, arranging an adhesive on a second different face of the mask tape;

wherein the mask tape comprises a window open to the second face of the substrate tape, wherein the window is sized and shaped to allow an integrated circuit to be inserted through the window and be subsequently mounted to the second face of the substrate tape after the mask tape has been attached to the substrate tape, and wherein the mask tape has a height greater than a height of an integrated circuit intended to be mounted on the second face of the substrate tape.

24. (New) A method as in claim 23 further comprising inserting the integrated circuit through the second face of the mask

tape through the window and subsequently fixing the integrated circuit against the second face of the substrate tape.

25. (New) A method as in claim 24 wherein inserting and fixing the integrated circuit occurs after the mask tape is glued to the substrate tape.

26. (New) A method as in claim 24 wherein the second face of the mask tape comprises a face opposite the first face of the mask tape.

27. (New) A method as in claim 24 wherein arranging the adhesive on the second different face of the mask tape occurs before the integrated circuit is fixed to the substrate tape

28. (New) A method as in claim 24 wherein arranging the adhesive on the second different face of the mask tape occurs after the integrated circuit is fixed to the substrate tape.